SDFS025B - D2942, MARCH 1987 - REVISED OCTOBER 1993

- 3-State True Outputs
- Back-to-Back Registers for Storage
- Package Options Include Plastic Small-Outline and Shrink Small-Outline Packages and Standard Plastic 300-mil DIPs

description

The SN74F543 octal transceiver contains two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (LEAB or LEBA) and output enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow. The A outputs are characterized to sink 24 mA while the B outputs are characterized to sink 64 mA.

DB, DW, OR NT PACKAGE (TOP VIEW)

				_
LEBA [1	\cup	24	□ v _{cc}
OEBA [2		23	CEBA
A1 [3		22] B1
A2 [4		21] B2
A3 [5		20] B3
A4 [6		19] B4
A5 [7		18] B5
A6 [8		17] B6
A7 [9		16] B7
A8 [10		15] B8
CEAB [11		14	LEAB
GND [12		13	OEAB

The A-to-B enable (CEAB) input must be low in order to enter data from A or to output data from B. Having CEAB low and LEAB low makes the A-to-B latches transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the CEBA, LEBA, and OEBA inputs.

The SN74F543 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN74F543 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE†

	INPUTS					
CEAB	LEAB	OEAB	Α	В		
Н	Х	Х	Χ	Z		
X	Χ	Н	Χ	Z		
L	Н	L	Χ	в ₀ ‡		
L	L	L	L	L		
L	L	L	Н	Н		

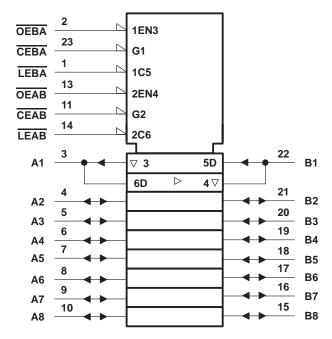
[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.



[‡] Output level before the indicated steady-state input conditions were established.

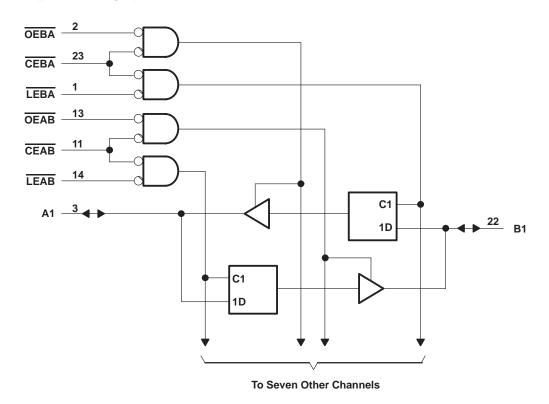
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logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (excluding I/O ports) (see Note 1)	1.2 V to 7 V
Input current range, I _{IK}	–30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state	0.5 V to 5.5 V
Voltage range applied to any output in the high state	0.5 V to V _{CC}
Current into any output in the low state: A1-A8	48 mÅ
B1-B8	128 mA
Operating free-air temperature range	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

				NOM	MAX	UNIT
V _{CC} Supply voltage			4.5	5	5.5	V
V _{IH} High-level input voltage			2			V
V _{IL} Low-level input voltage					0.8	V
lıK	Input clamp current				-18	mA
10	High-level output current A1 – A8 B1 – B8			-3	mA	
ЮН				-15	111/2	
la.	Low lovel output ourrest	A1-A8			24	mA
IOL	Low-level output current B1-B8				64	IIIA
TA	T _A Operating free-air temperature				70	°C

NOTE 1: The input-voltage ratings may be exceeded provided the input-current ratings are observed.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT	
٧ıK		$V_{CC} = 4.5 \text{ V},$	I _I = – 18 mA			-1.2	V	
	A1-A8		$I_{OH} = -1 \text{ mA}$	2.5	3.4			
	AT-AO	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$I_{OH} = -3 \text{ mA}$	2.4	3.3			
Vон	B1-B8	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.3		V	
	D1-D0		$I_{OH} = -15 \text{ mA}$	2	3.1			
	Any output	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA to } -3 \text{ mA}$	2.7				
\/o;	A1-A8	V _{CC} = 4.5 V	I _{OL} = 24 mA		0.3	0.5	- V	
VOL	B1-B8	VCC = 4.5 V	I _{OL} = 64 mA		0.42	0.55		
1.	OE, LE, and CE	V FV	V _I = 7 V			0.1	mA	
l _l	A and B ports	V _{CC} = 5.5 V	V _I = 5.5 V			1	IIIA	
. +	OE, LE, and CE	V	V _I = 2.7 V			20	μΑ	
I _{IH} ‡	A and B ports	$V_{CC} = 5.5 \text{ V},$				70		
. +	OE, LE, and CE	V _{CC} = 5.5 V,	V: 0.5.V			-1.2	A	
I _{IL} ‡	A and B ports	vCC = 5.5 v,	V _I = 0.5 V			-0.65	mA	
	A1-A8	V F	V _O = 0	-60		-150	mA	
I _{OS} §	B1-B8	V _{CC} = 5.5 V,		-100		-225		
ICCH		V _{CC} = 5.5 V			67	100	mA	
ICCL	·	V _{CC} = 5.5 V			83	125	mA	
I _{CCZ}		V _{CC} = 5.5 V			83	125	mA	

timing requirements

				= 5 V, 25°C	V _{CC} = 4.5 V to 5.5 V, T _A = MIN to MAX¶		UNIT
			MIN	MAX	MIN	MAX	
t _W Pulse duration		5		5		ns	
t _{su}	Setup time, data before latch enable	High or low	3		3.5		ns
th	t _h Hold time, data after latch enable High or low		3		3.5		ns

[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics (see Note 2)

PARAMETER FROM (INPUT)		TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = 25^{\circ}\text{C}$			$V_{CC} = 4.5$ $C_L = 50 \text{ pF}$ $R_L = 500 \Omega$ $T_A = \text{MIN t}$	UNIT	
			MIN	TYP	MAX	MIN	MAX	
^t PLH	A or B	B or A	2.2	5.1	7.5	2.2	8.5	ns
^t PHL		BULK	2.2	4.6	6.5	2.2	7.5	115
t _{PLH}	LEBA	А	3.7	8.1	11	4.1	12.5	no
t _{PHL}		A	3.7	8.1	11	4.1	12.5	ns
t _{PLH}	LEAB	В	3.7	8.1	11	4.1	12.5	20
^t PHL	LEAB	Ь	3.7	8.1	11	4.1	12.5	ns
^t PZH	0 0	A or D	2.2	6.6	9	2.2	10	
t _{PZL}	OE or CE	A or B	3.2	7.1	10.5	3.2	12	ns
^t PHZ	OE or CE	A or B	1.7	5.6	8	1.7	9	20
t _{PLZ}		AUID	1.7	5.1	7.5	1.7	8.5	ns

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and waveforms are shown in Section 1.



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